

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L2 | 1721 | program\$4 and interconnect and metal adj layer\$1 and via\$1 and potential\$1 | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | OFF | 2006/02/05 15:33 |

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|--------------------------|------------------|---------|------------------|
| L1 | 2 | memory and chip and voltage adj supply and metal adj layer\$1 and ladder and output and interconnect | USPAT; EPO; JPO; DERWENT | OR | OFF | 2006/02/05 15:52 |
| L2 | 171 | memory and chip and voltage adj supply and metal adj layer\$1 and via\$1 and output and interconnect | USPAT; EPO; JPO; DERWENT | OR | OFF | 2006/02/05 15:52 |